

SUBSTITUTE SPECIFICATION: CLEAN VERSION

14603-010US1/ P2002,0604USN
U.S. Application No. 10/521,322

METHOD FOR PRODUCING AN ELECTRICAL COMPONENT

TECHNICAL FIELD

This patent application relates to a method for producing submerged bondable
5 terminal pads on a component which includes at least two interconnected substrates.

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BACKGROUND

It is known from published patent specification WO98/05935A1 that sensors can
be placed on a substrate in such a way that the sensor elements are positioned over an
10 opening in the substrate. It is known from published patent specification JP
2000195827A as well as in the quotation in Patent Abstracts of Japan to place grooves on
one side of a substrate, and in order to separate the LED components formed on a wafer to
make incisions from the back side of the substrate over the grooves to such a depth that
the grooves are opened. In the case of two connected substrates, it is known from
15 published patent specification JP09223678A that the procedure is to remove cutouts from
a second substrate to separate the components.

Examples of components that are realized in two connected substrates are so-
called COC (chip on chip) components which have a type of vertical integration. The two
20 substrates which both component structures can have are interconnected through two main
surfaces, while at the same time, if necessary, an electrical contact can be established